

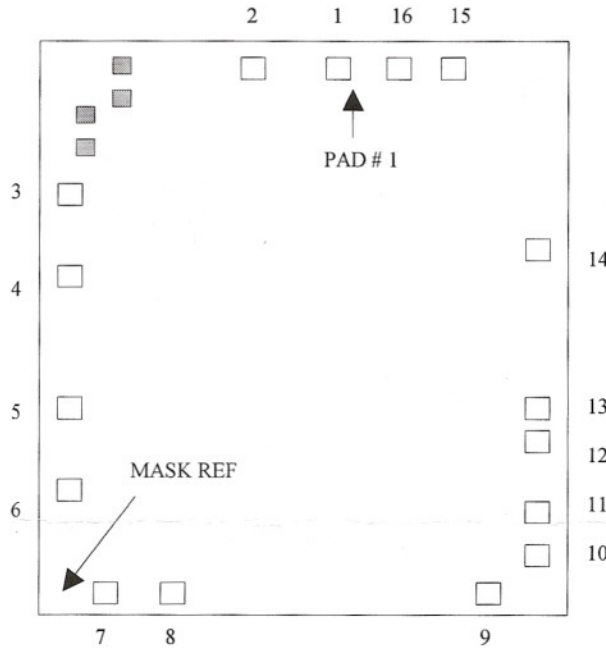


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PAD FUNCTIONS

1. "9" OUT
2. C
3. D
4. SET TO "9"
5. NOT OUT
6. OUT
7. INHIBIT OUT (CARRY)
8. Vss
9. CLOCK
10. STROBE
11. INHIBIT IN (CARRY)
12. CASCADE
13. CLEAR
14. A
15. B
16. VDD



The information given is believed to be correct at the time of issue.

Please verify your requirements prior to commencement of any assembly process, as no liability for omission or error can be accepted.

Chip back potential is the level at which bulk silicon is maintained either by bond pad connection or in some cases the potential to which the chip back must be connected if stated above.

Note: 1 mil = 0.001inch

APPROVED

BEN WHITE

DATE: 22/02/2005

CD4527B

TEXAS INSTRUMENTS

DIE INFORMATION

DIMENSIONS (Mils): 99 x 85 x 25
 BOND PADS (Mils): 4 x 4
 MASK REF: CD4527B
 GEOMETRY:
 BACK POTENTIAL:

METALLISATION

TOP: Al
 BACK: Si